

## PEREGRINE MATERIAL DECLARATION FORM

<b>Product:</b>	PE4140
<b>Ordering Codes:</b>	PE4140B-Z
<b>Description:</b>	UltraCMOS® Ultra-High Linearity Broadband Quad MOSFET Array
<b>Package:</b>	6L 3x3 DFN
<b>Environmental Compliance</b>	EU RoHS2 Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free, JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
<b>Lead Finish</b>	Sn
<b>Availability</b>	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	0.314215	1.50%	14,958.48
Die	Aluminum	7429-90-5	0.000956	0.00%	45.50
Die	Silicon	7440-21-3	0.000064	0.00%	3.03
Die	Arsenic	7440-38-2	0.000000	0.00%	0.02
Die	Boron	7440-42-8	0.000000	0.00%	0.02
Die	Phosphorus	7723-14-0	0.000001	0.00%	0.06
Die	Titanium	7440-32-6	0.000159	0.00%	7.58
Die	Tungsten	7440-33-7	0.003186	0.02%	151.67
Die	Cobalt	7440-48-4	0.000006	0.00%	0.30
Die	Copper	7440-50-8	0.000003	0.00%	0.12
Leadframe	Copper	7440-50-8	7.795600	37.11%	371,116.72
Leadframe	Iron	7439-89-6	0.187900	0.89%	8,945.15
Leadframe	Zinc	7440-66-6	0.009600	0.05%	457.02
Leadframe	Phosphorus	7723-14-0	0.002400	0.01%	114.25
Leadframe	Silver	7440-22-4	0.206400	0.98%	9,825.86
Die Attach	Silver	7440-22-4	0.199900	0.95%	9,516.42
Die Attach	Epoxy Resin	9003-36-5	0.050000	0.24%	2,380.30
Die Attach	t-Butyl phenyl glycidyl ether	3101-60-8	0.020800	0.10%	990.20
Die Attach	Phenolic harder	92-88-6	0.004200	0.02%	199.94
Die Attach	Butyl cellosolve acetate	112-07-2	0.002800	0.01%	133.30
Gold Wire	Gold	7440-57-5	0.088500	0.42%	4,213.12
Plating	Tin	7440-31-5	0.114900	0.55%	5,469.92
Mold Compound	Silica Fused	60676-86-0	11.007800	52.40%	524,036.46
Mold Compound	Epoxy Resin	Trade secret	0.480200	2.29%	22,860.36
Mold Compound	Phenol Resin	Trade secret	0.480200	2.29%	22,860.36
Mold Compound	Carbon Black	1333-86-4	0.036000	0.17%	1,713.81
<b>Total Weight (mg)</b>			<b>21.005790</b>	100.00%	1,000,000